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Data sheet acquired from Harris Semiconductor
SCHS039C - Revised September 2003

CMOS Quad True/Complement Buffer

High Voltage Types (20-Volt Rating)

■ CD4041UB types are quad true/complement buffers consisting of n- and p-channel units having low channel resistance and high current (sourcing and sinking) capability. The CD4041UB is intended for use as a buffer, line driver, or CMOS-to-TTL driver. It can be used as an ultra-low power resistor-network driver for A/D and D/A conversion, as a transmission-line driver, and in other applications where high noise immunity and low power dissipation are primary design requirements.

The CD4041UB types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

MAXIMUM RATINGS, Absolute-Maximum Values: DC SUPPLY-VOLTAGE RANGE, (V_{DD})

Voltages referenced to V_{SS} Terminal) -0.5 to +20V
INPUT VOLTAGE RANGE, ALL INPUTS -0.5 to V_{DD} +0.5V

DC INPUT CURRENT, ANY ONE INPUT ±10mA

POWER DISSIPATION PER PACKAGE (P_D):

For T_A = -55°C to +100°C 500mW
For T_A = +100°C to +125°C Derate Linearity at 12mW/°C to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW

OPERATING-TEMPERATURE RANGE (T_A) -55°C to +125°C

STORAGE TEMPERATURE RANGE (T_{stg}) -65°C to +150°C

LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max +265°C

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following range:

CHARACTERISTIC	LIMITS		UNITS
	Min.	Max.	
Supply-Voltage Range (For T _A =Full Package- Temperature Range)	3	18	V

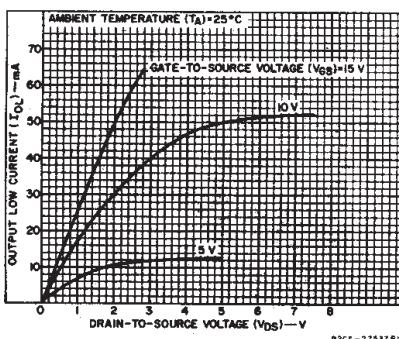


Fig.2 - Typical output low (sink) current characteristics.

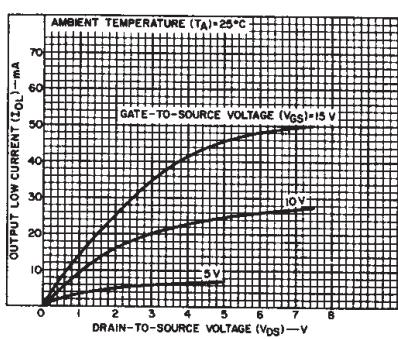


Fig.3 - Minimum low (sink) current characteristics.

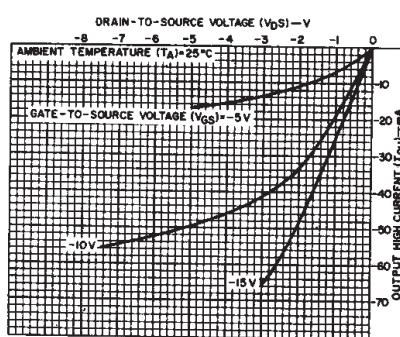


Fig.4 - Typical output high (source) current characteristics.

CD4041UB Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)						UNITS
				-55	-40	+85	+125	+25		
	V_O (V)	V_{IN} (V)	V_{DD} (V)	Min.	Typ.	Max.				
Quiescent Device Current I_{DD} Max.	-	0.5	5	1	1	30	30	-	0.02	1
	-	0.10	10	2	2	60	60	-	0.02	2
	-	0.15	15	4	4	120	120	-	0.02	4
	-	0.20	20	20	20	600	600	-	0.04	20
Output Low (Sink) Current, I_{OL} Min.	0.4	0.5	5	2.1	1.8	1.3	1.2	1.6	3.2	-
	0.5	0.10	10	6.25	5.6	4	3.5	5	10	-
	1.5	0.15	15	24	23	15.5	13	19	38	-
	4.6	0.5	5	-2.1	-1.8	-1.3	-1.2	-1.6	-3.2	-
Output High (Source) Current, I_{OH} Min.	2.5	0.5	5	-8.4	-6.7	-5.3	-4.6	-6.4	-12.8	-
	9.5	0.10	10	-6.25	-5.6	-4	-3.5	-5	-10	-
	13.5	0.15	15	-24	-23	-15.5	-13	-19	-38	-
	-	0.5	5	0.05			-	0	0.05	-
Output Voltage: Low-Level, V_{OL} Max.	-	0.10	10	0.05			-	0	0.05	-
	-	0.15	15	0.05			-	0	0.05	-
	-	0.5	5	4.95			4.95	5	-	-
Output Voltage: High-Level, V_{OH} Min.	-	0.10	10	9.95			9.95	10	-	-
	-	0.15	15	14.95			14.95	15	-	-
	0.5, 4.5	-	5	1			-	-	1	-
Input Low Voltage, V_{IL} Max.	1.9	-	10	2			-	-	2	-
	1.5, 13.5	-	15	2.5			-	-	2.5	-
	0.5, 4.5	-	5	4			4	-	-	-
Input High Voltage, V_{IH} Min.	1.9	-	10	8			8	-	-	-
	1.5, 13.5	-	15	12.5			12.5	-	-	-
Input Current, I_{IN} Max.	-	0.18	18	± 0.1	± 0.1	± 1	± 1	-	$\pm 10^{-5}$	± 0.1
										μA

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ C$, Input $t_r, t_f = 20$ ns, $C_L = 50$ pF, $R_L = 200$ k Ω

CHARACTERISTIC	CONDITIONS			LIMITS			UNITS
				V_{DD} Volts	Typ.	Max.	
Propagation Delay Time: t_{PHL}, t_{PLH}				5	60	120	ns
				10	35	70	
				15	25	50	
Transition Time t_{THL}, t_{TLH}				5	40	80	ns
				10	20	40	
				15	15	30	
Input Capacitance C_{IN}	Any Input			15	22.5	pF	

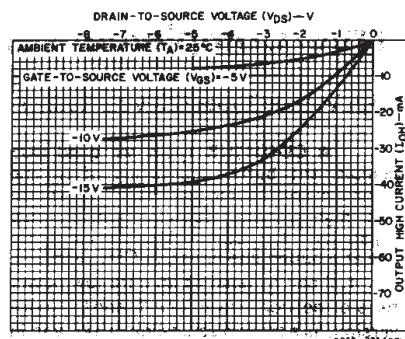


Fig.5 – Minimum output high (source) current characteristics.

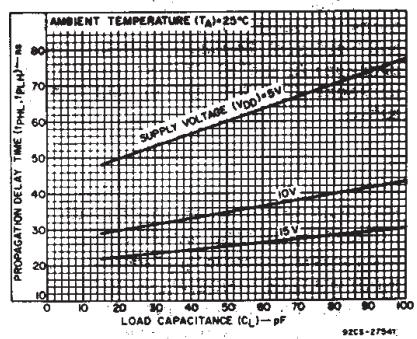


Fig.6 – Typical propagation delay time vs. load capacitance.

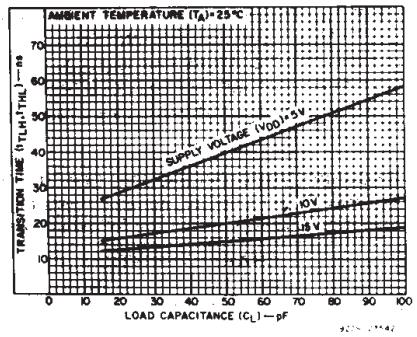


Fig.7 – Typical transition time vs. load capacitance.

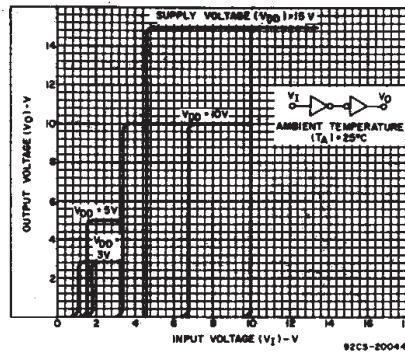


Fig.8 – Minimum and maximum transfer characteristics – true output.

CD4041UB Types

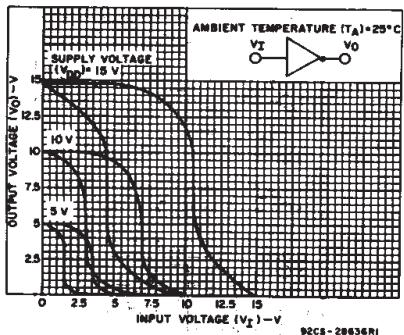


Fig.9 – Minimum and maximum transfer characteristics – complement output.

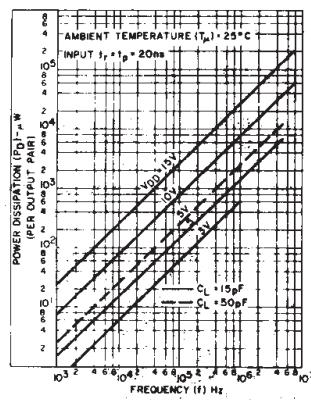


Fig.11 – Typical power dissipation vs frequency per output pair.

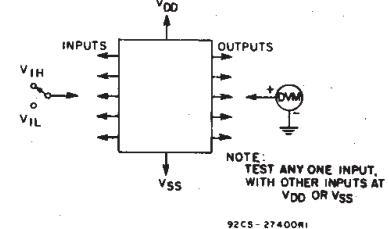


Fig.13 – Input voltage test circuit.

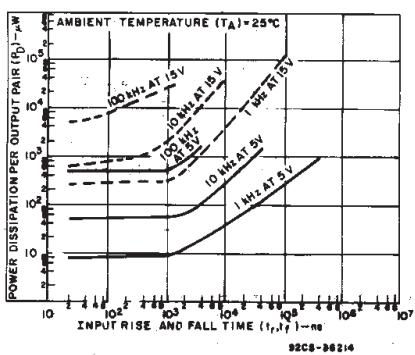


Fig.10 – Typical power dissipation vs. input rise & fall time per output pair.

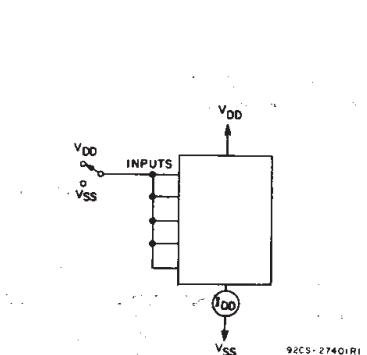


Fig.12 – Quiescent device current test circuit.

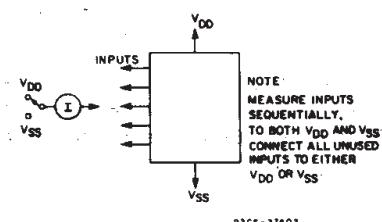
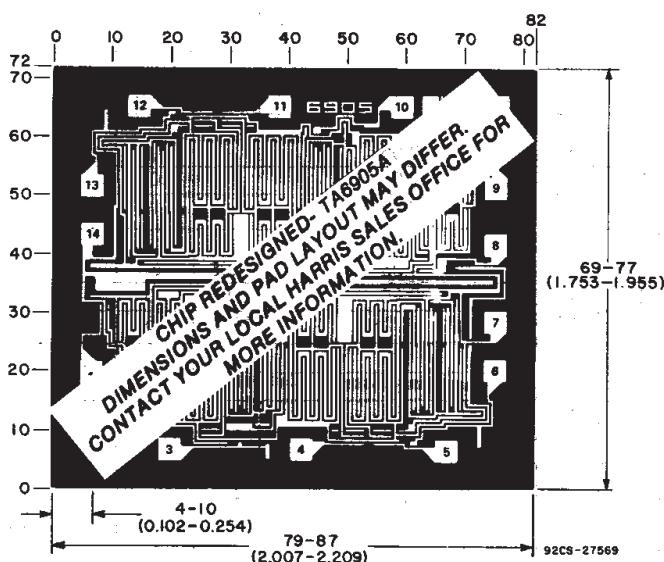


Fig.14 – Input-leakage-current test circuit.

Dimensions and pad layout for the CD4041UBH



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD4041UBE	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4041UBE	Samples
CD4041UBEE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4041UBE	Samples
CD4041UBF	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD4041UBF	Samples
CD4041UBF3A	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD4041UBF3A	Samples
CD4041UBM	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4041UBM	Samples
CD4041UBM96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4041UBM	Samples
CD4041UBMG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4041UBM	Samples
CD4041UBMT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4041UBM	Samples
CD4041UBPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM041UB	Samples
CD4041UBPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM041UB	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD4041UB, CD4041UB-MIL :

• Catalog: [CD4041UB](#)

• Military: [CD4041UB-MIL](#)

NOTE: Qualified Version Definitions:

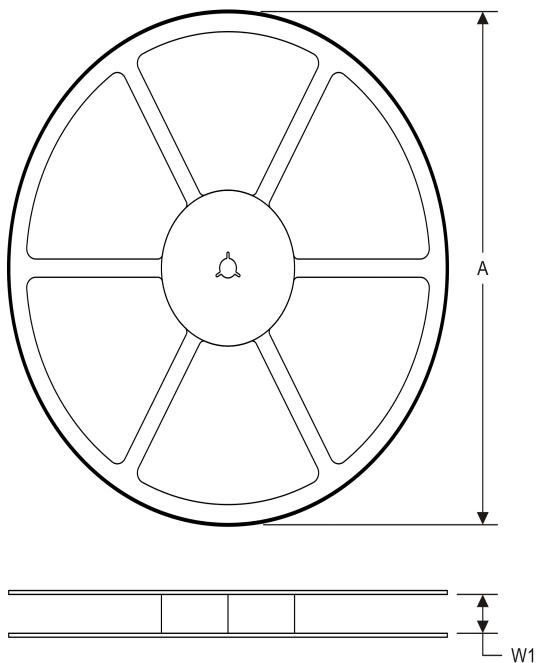
• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

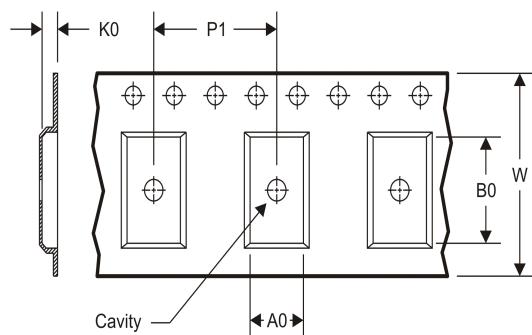
PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



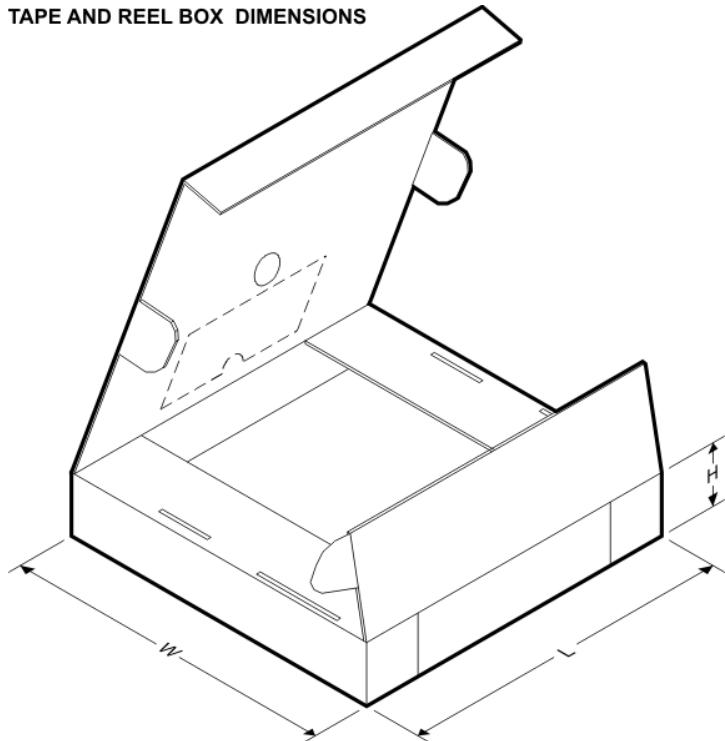
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4041UBM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4041UBMT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4041UBPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



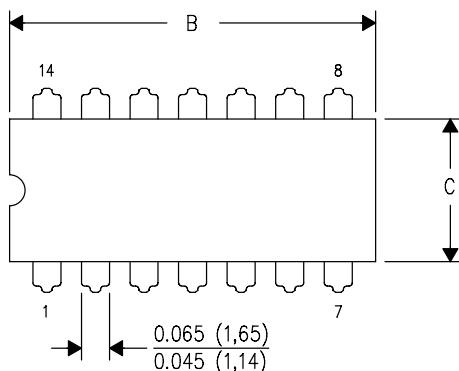
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4041UBM96	SOIC	D	14	2500	367.0	367.0	38.0
CD4041UBMT	SOIC	D	14	250	367.0	367.0	38.0
CD4041UBPWR	TSSOP	PW	14	2000	367.0	367.0	35.0

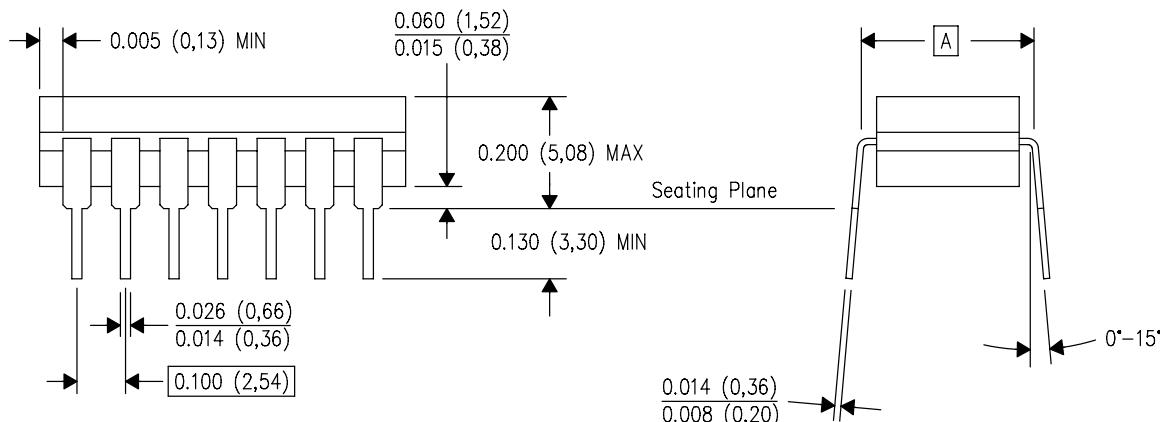
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM	PINS **	14	16	18	20
		A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX		0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN		—	—	—	—
C MAX		0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN		0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:

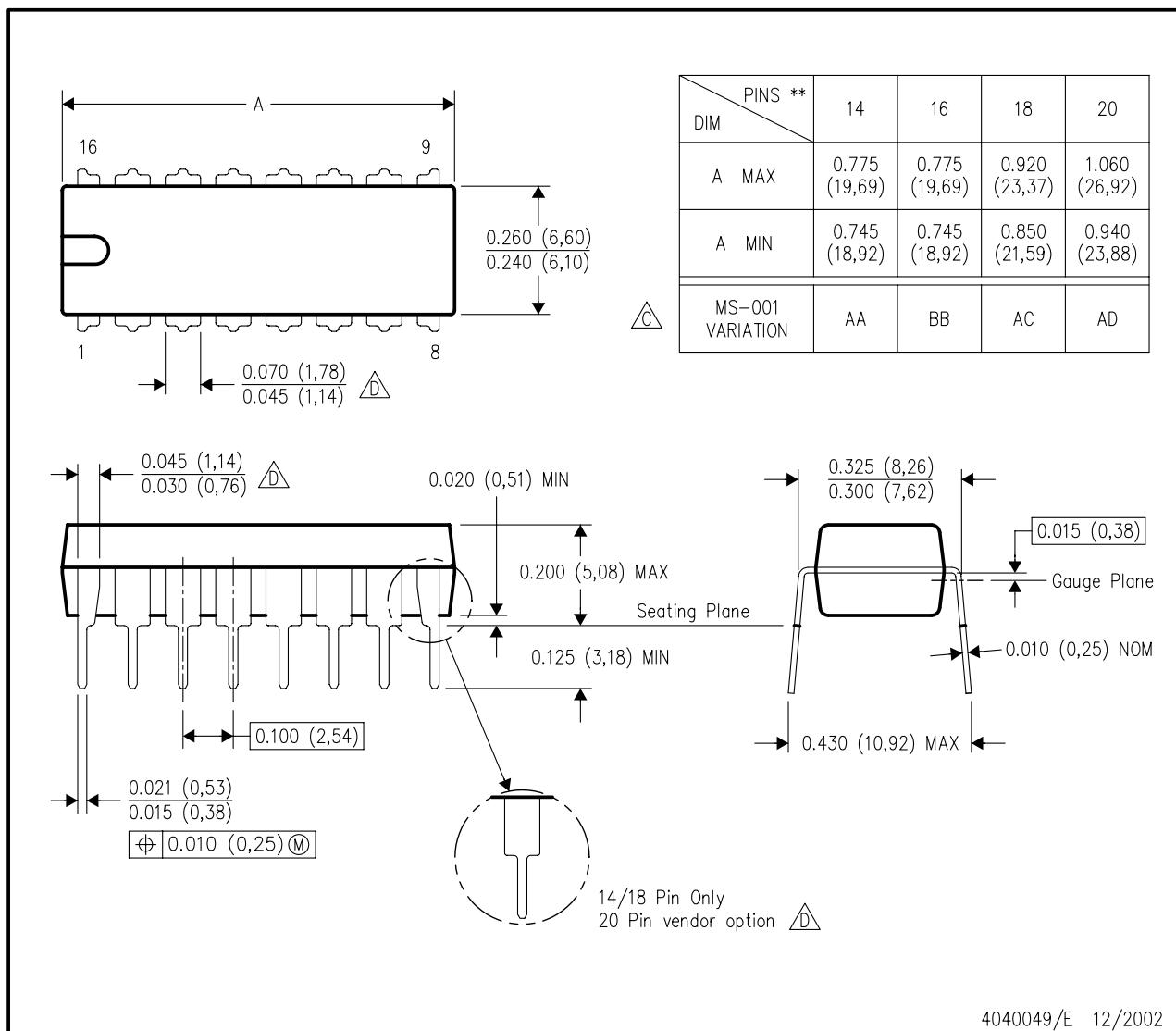
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

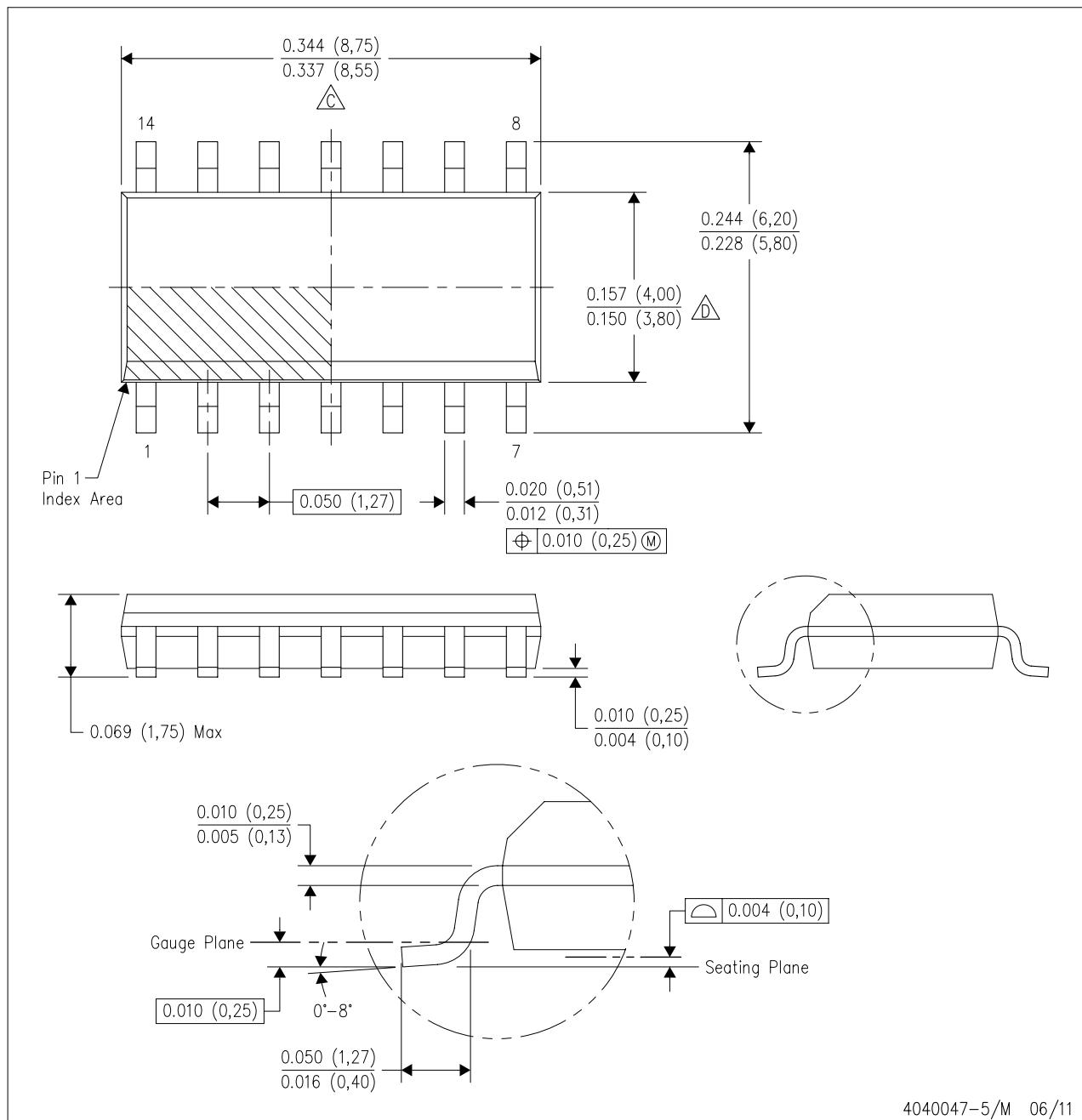
Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.

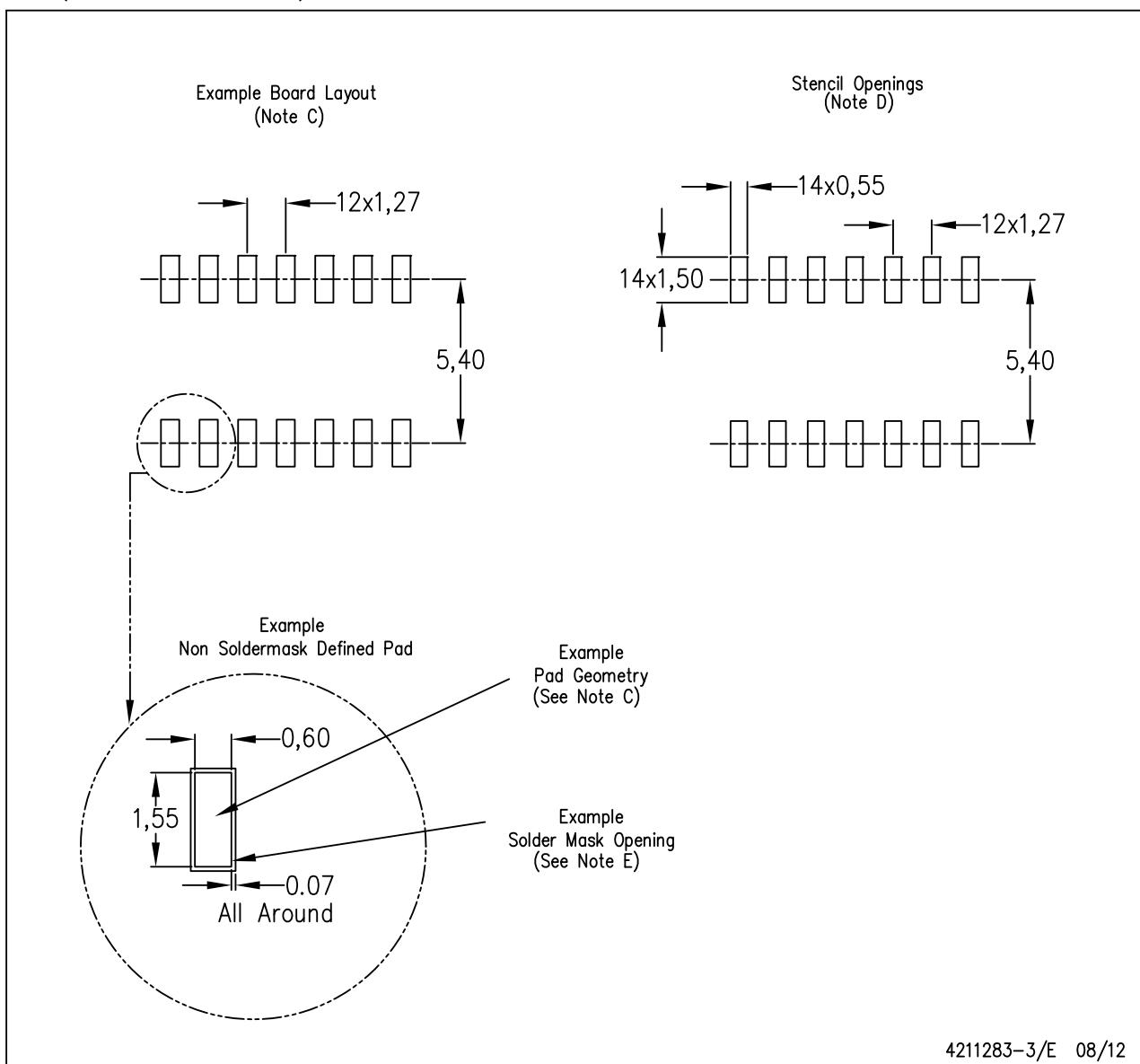
$\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS-012 variation AB.

4040047-5/M 06/11

LAND PATTERN DATA

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



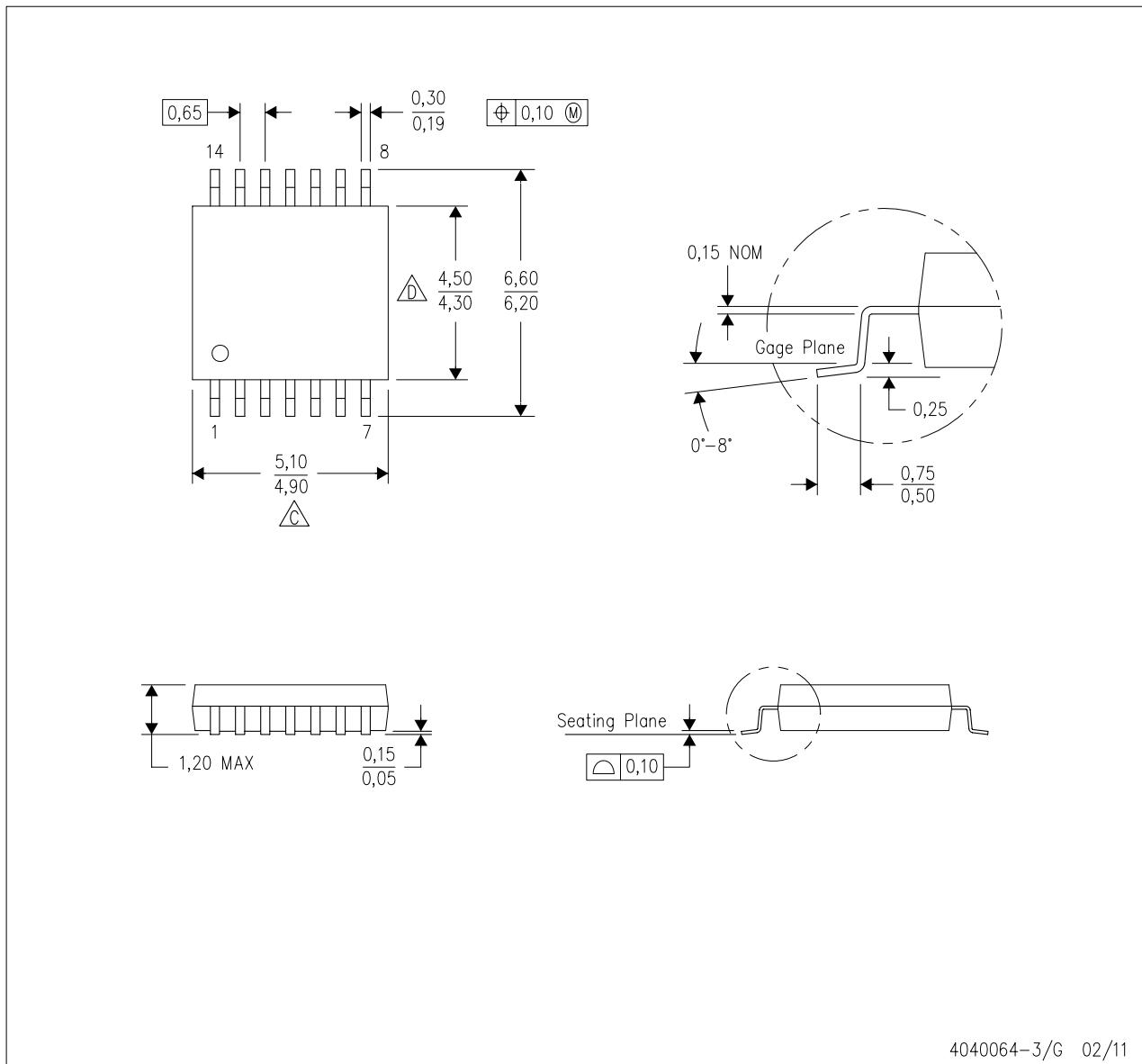
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040064-3/G 02/11

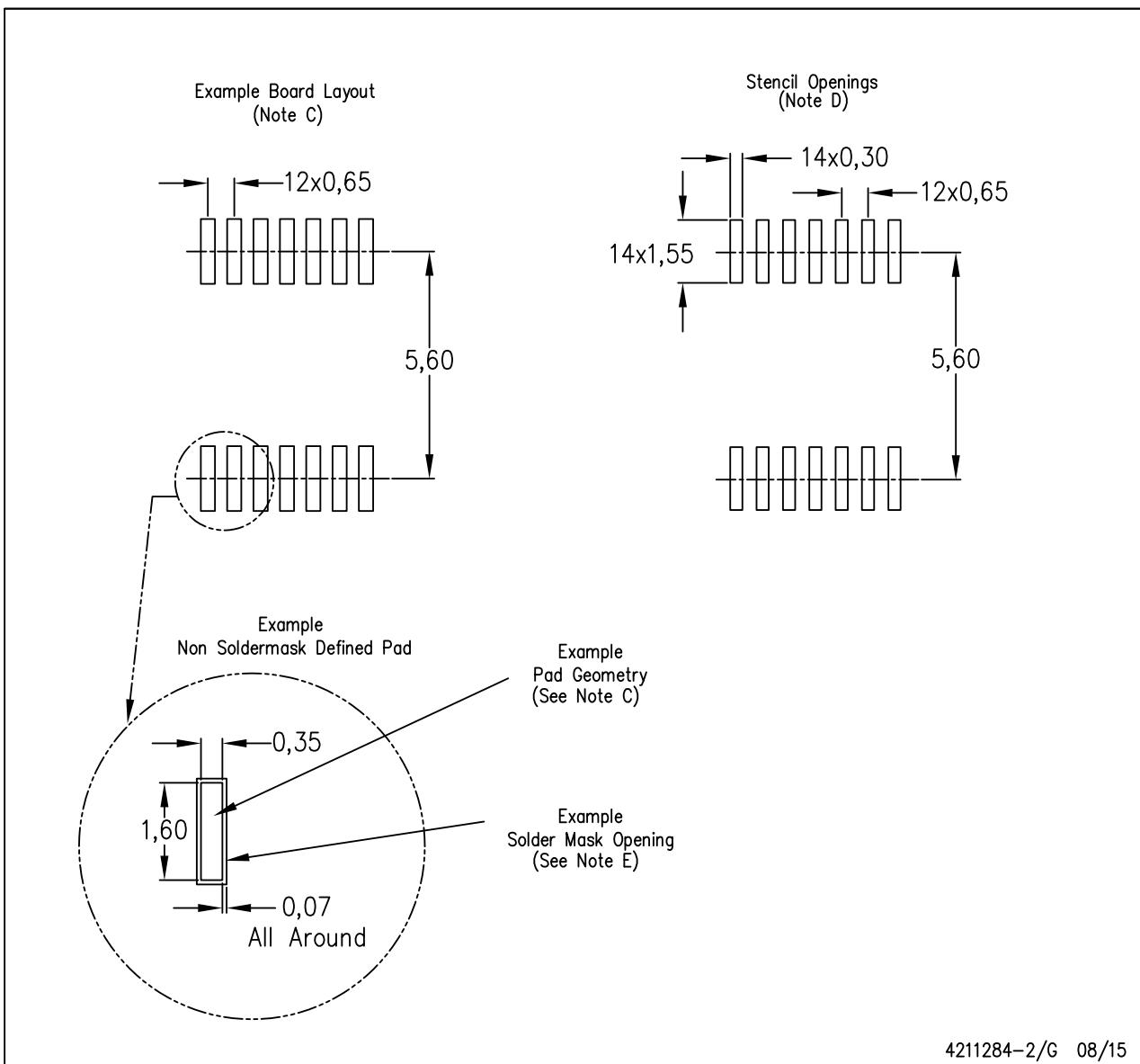
NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153

LAND PATTERN DATA

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211284-2/G 08/15

NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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